



- Β. This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side. C.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad
- Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <a href="http://www.ti.com">http://www.ti.com</a>. Falls within JEDEC MO-153 Variation DBT.

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